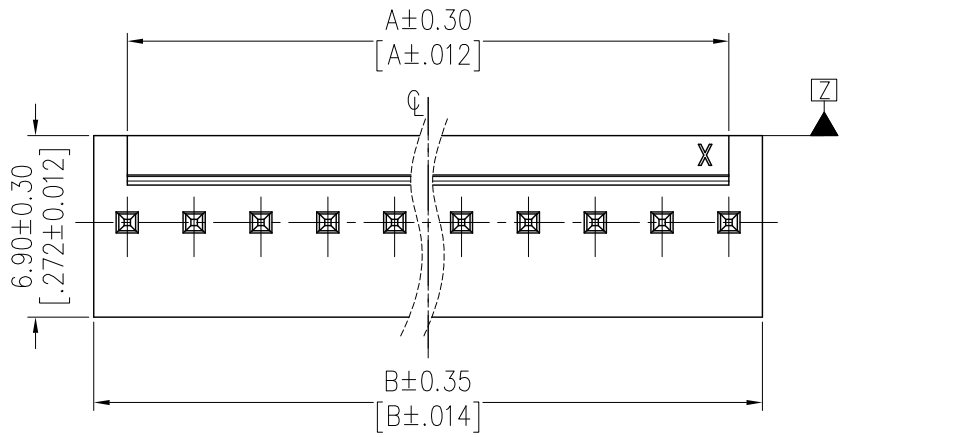
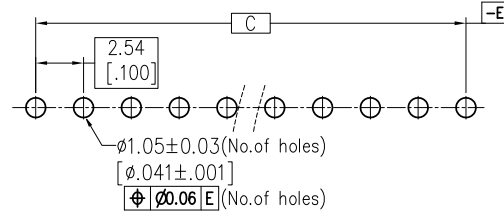


MAS-CON HEADER, Series 100, 2.54mm, 180° unbreakable, with locking, with polarization



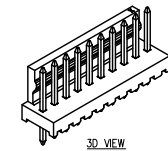
Recommended P.C.B Layout(Top Side)
(PCB BOARD TOLERANCE±0.05)
PCB BOARD THICKNESS:1.6~2.0



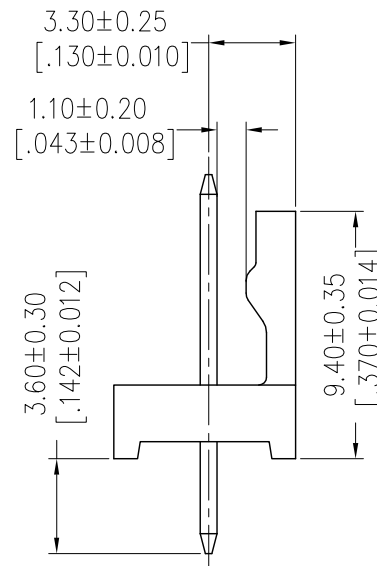
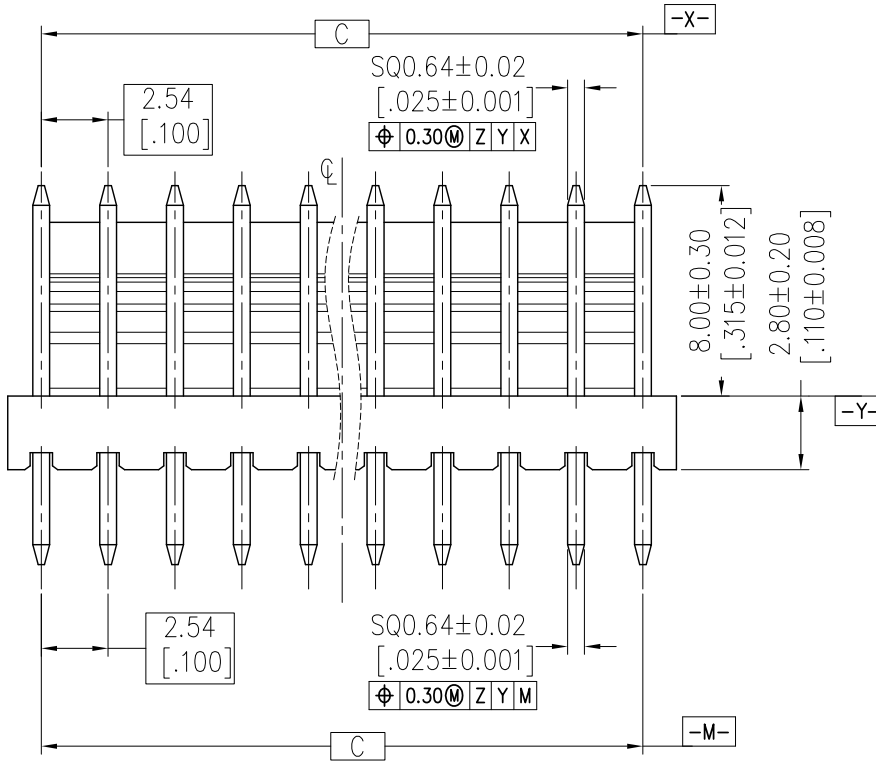
NOTES:
Current Rating: 3,0 AMP
Contact Resistance: 20mΩ max.
Withstand Voltage: 1000V AC/Minute
Insulation Resistance: 1000MΩ min.
Operation Temperature: -40°C to +105°C

Contact Material: Copper Alloy
Contact Plating: Sn over Ni (Au on request)
Insulator Material: PA66 GF (UL94 V-0)

Recommended Process:
Wave Soldering
Peak Temperature: 235±5°C



OPERATION	
X.X	±0.40
X.XX	±0.25
X.XXX	±0.15
Angle	± 3°
DIM	TOL



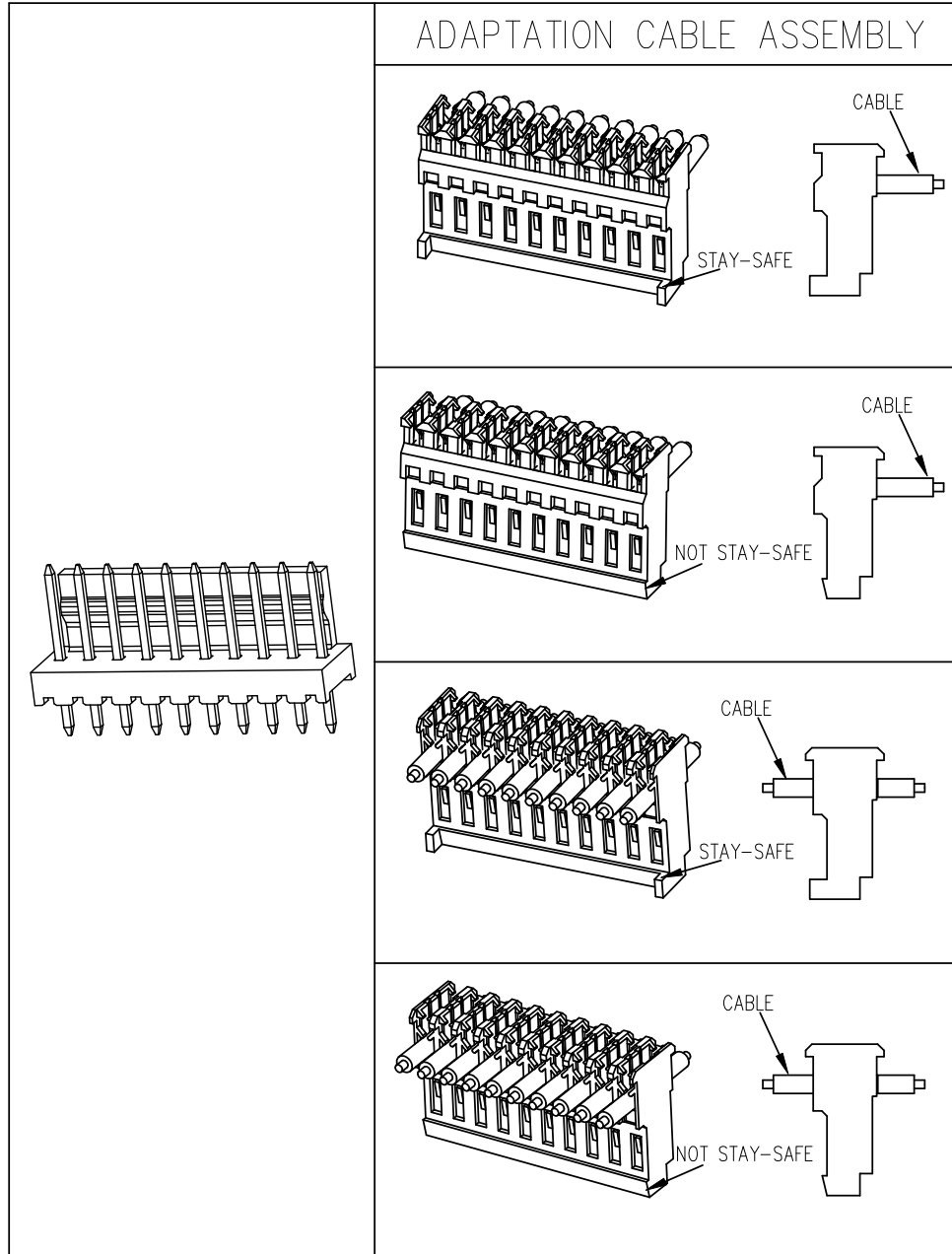
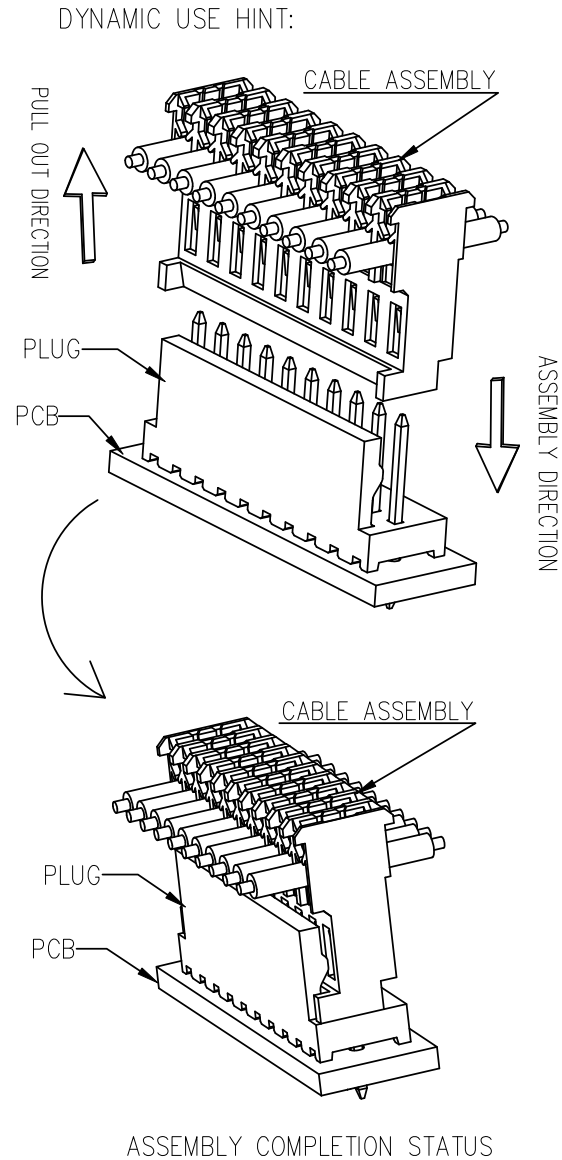
MUSS100- XX - X X _ E

No. Of Positions	02 - 36
02 - 05 Positions:	D (500Parts/Bag)
06 - 40 Positions:	C (100Parts/Bag)
Tin :	no remark
Gold :	A
Gold / Tin :	B

Sheet 1 of 2

REV	DATE	NOTE	NAME
4	07.06.2021	PN for Au added	JAL
3	25.08.2020	DRW revised	JAL
2	21.01.2020	comp. Revised	LAD
1	26.11.2019	issued	LAD

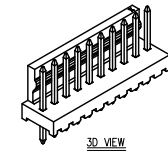
MAS-CON HEADER, Series 100, 2.54mm, 180° unbreakable, with locking, with polarization



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Sheet 2 of 2

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